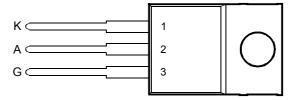
- 5 A Continuous On-State Current
- 30 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I<sub>GT</sub> of 200 μA

#### TO-220 PACKAGE (TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDC1ACA

## absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT	
	TIC106D		400		
Repetitive peak off-state voltage (see Note 1)	TIC106M	V	600	V	
	TIC106S	$V_{DRM}$	700		
	TIC106N		800	1	
Repetitive peak reverse voltage	TIC106D		400		
	TIC106M	V	600	V	
	TIC106S	$V_{RRM}$	700		
	TIC106N		800		
Continuous on-state current at (or below) 80°C case temperature (see Note 2)		I <sub>T(RMS)</sub>	5	Α	
Average on-state current (180° conduction angle) at (or below) 80°C case temperature			3.2	А	
(see Note 3)		I <sub>T(AV)</sub>	5.2		
Surge on-state current at (or below) 25°C (see Note 4)		I <sub>TSM</sub>	30	Α	
Peak positive gate current (pulse width ≤ 300 μs)		I <sub>GM</sub>	0.2	Α	
Peak gate power dissipation (pulse width ≤ 300 μs)		$P_{GM}$	1.3	W	
Average gate power dissipation (see Note 5)		$P_{G(AV)}$	0.3	W	
Operating case temperature range			-40 to +110	°C	
Storage temperature range	T <sub>stg</sub>	-40 to +125	°C		
Lead temperature 1.6 mm from case for 10 seconds			230	°C	

- NOTES: 1. These values apply when the gate-cathode resistance  $R_{GK}$  = 1 k $\Omega$ .
  - 2. These values apply for continuous dc operation with resistive load. Above 80°C derate linearly to zero at 110°C.
  - 3. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 80°C derate linearly to zero at 110°C.
  - 4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
  - 5. This value applies for a maximum averaging time of 20 ms.



# TIC106 SERIES SILICON CONTROLLED RECTIFIERS

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# electrical characteristics at 25°C case temperature (unless otherwise noted)

	PARAMETER		TEST CONDITION	ONS	MIN	TYP	MAX	UNIT
I <sub>DRM</sub>	Repetitive peak off-state current	V <sub>D</sub> = rated V <sub>DRM</sub>	R <sub>GK</sub> = 1 kΩ	T <sub>C</sub> = 110°C			400	μΑ
I <sub>RRM</sub>	Repetitive peak reverse current	V <sub>R</sub> = rated V <sub>RRM</sub>	I <sub>G</sub> = 0	T <sub>C</sub> = 110°C			1	mA
I <sub>GT</sub>	Gate trigger current	V <sub>AA</sub> = 12 V	$R_L = 100 \Omega$	t <sub>p(g)</sub> ≥ 20 μs		5	200	μΑ
V <sub>GT</sub> Gate trigger vo		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20  \mu\text{s}$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$	$T_C = -40^{\circ}C$			1.2	
	Gate trigger voltage	$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20  \mu\text{s}$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$		0.4	0.6	1	٧
		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20  \mu\text{s}$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$	T <sub>C</sub> = 110°C	0.2			
I <sub>H</sub>	Holding current	$V_{AA} = 12 \text{ V}$ Initiating $I_T = 10 \text{ mA}$	$R_{GK} = 1 k\Omega$	T <sub>C</sub> = - 40°C			8	mA
		$V_{AA} = 12 \text{ V}$ Initiating $I_T = 10 \text{ mA}$	$R_{GK} = 1 k\Omega$				5	111/5
V <sub>T</sub>	Peak on-state voltage	I <sub>T</sub> = 5 A	(See Note 6)				1.7	٧
dv/dt	Critical rate of rise of off-state voltage	V <sub>D</sub> = rated V <sub>D</sub>	R <sub>GK</sub> = 1 kΩ	T <sub>C</sub> = 110°C		10		V/µs

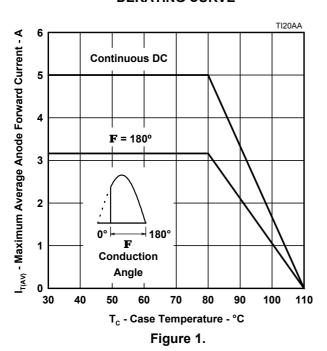
NOTE 6: This parameter must be measured using pulse techniques,  $t_p = 300 \mu s$ , duty cycle  $\leq 2 \%$ . Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

#### thermal characteristics

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			3.5	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

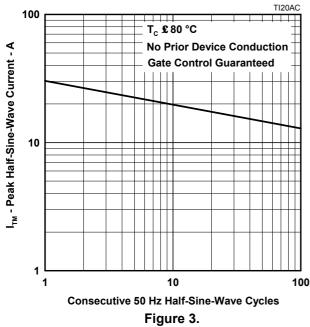
#### THERMAL INFORMATION

# **AVERAGE ANODE ON-STATE CURRENT DERATING CURVE**

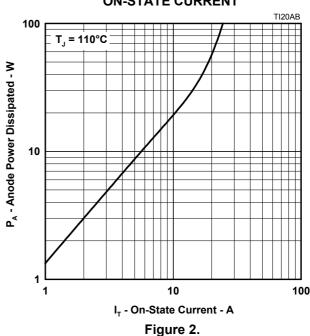


# **SURGE ON-STATE CURRENT** VS

# **CYCLES OF CURRENT DURATION**

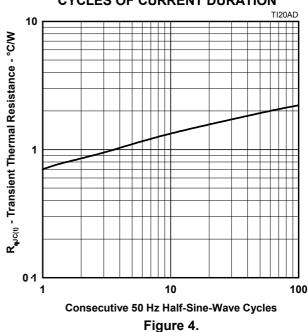


## **ANODE POWER DISSIPATED** vs **ON-STATE CURRENT**

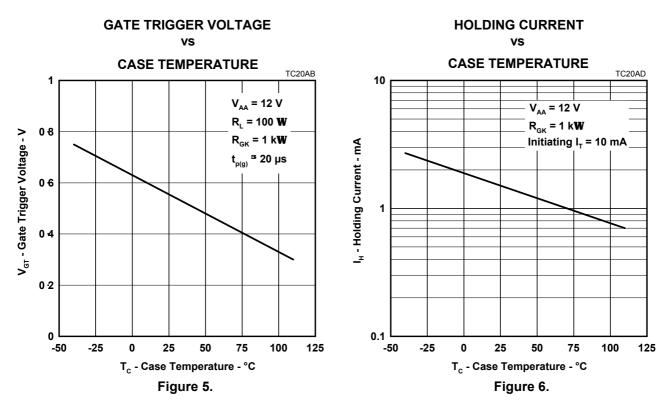


## TRANSIENT THERMAL RESISTANCE VS

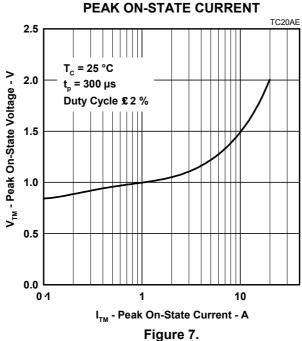
#### **CYCLES OF CURRENT DURATION**



#### **TYPICAL CHARACTERISTICS**



# PEAK ON-STATE CURRENT

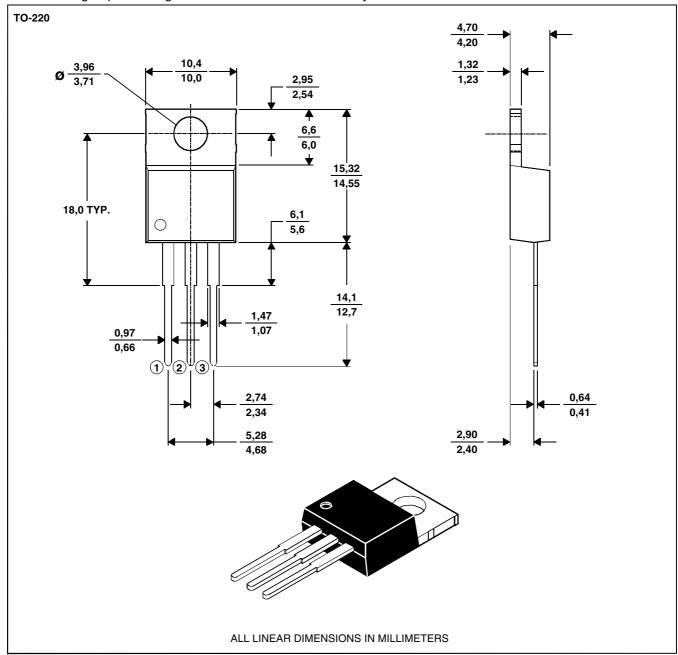


#### **MECHANICAL DATA**

#### **TO-220**

## 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.



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